


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	MDG/22/13736	
<b>1.3 Title of PCN</b>	SAMSUNG Foundry (South Korea) additional source for STM32H7Ax & STM32H7Bx 2MB listed products	
<b>1.4 Product Category</b>	STM32H7Ax, STM32H7Bx	
<b>1.5 Issue date</b>	2022-11-24	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	KRAUSE INA
<b>2.1.2 Phone</b>	+49 89460062370
<b>2.1.3 Email</b>	ina.krause@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Ricardo Antonio DE SA EARP
<b>2.1.2 Marketing Manager</b>	Veronique BARLATIER
<b>2.1.3 Quality Manager</b>	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication	ST Crolles (France) SAMSUNG Foundry (South Korea)

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	Front-end source: - ST Crolles 12" France	Front-end sources: - ST Crolles 12" (France) - SAMSUNG Foundry 12" (South Korea) - added source There is no change in the product functionality. Please refer to PCN 13736 – Additional information attached document.
<b>4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?</b>	Packaged products : no change.	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Due to the success on the market of STM32 devices, ST General Purpose Microcontroller division decided to qualify an additional front-end site to maintain state of the art service level to our customers thanks to extra capacity.
<b>5.2 Customer Benefit</b>	CAPACITY INCREASE

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	Change is visible through diffusion traceability plant, on the marking: - "VQ" for ST Crolles 12" (France) - "LM" for SAMSUNG 12" (South Korea)
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2023-03-20
<b>7.2 Intended start of delivery</b>	2023-03-20
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	13736 MDG-GPM-RER2203 -PCN13736- eSTM40 tranfer to Samsung Foundry for STM32H7 (die 480) - Reliability Plan.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2022-11-24

**9. Attachments (additional documentations)**

13736 Public product.pdf  
13736 MDG-GPM-RER2203 -PCN13736- eSTM40 tranfer to Samsung Foundry for STM32H7 (die 480) - Reliability Plan.pdf  
13736 PCN13736\_Additional information.pdf

**10. Affected parts**

<b>10. 1 Current</b>		<b>10.2 New (if applicable)</b>
<b>10.1.1 Customer Part No</b>	<b>10.1.2 Supplier Part No</b>	<b>10.1.2 Supplier Part No</b>
3381460	STM32H7A3LIH6Q	
	STM32H7A3VGT6	
3515803	STM32H7A3VIT6	

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